L Number	Hits	Search Text	DB	Time stamp
4	21	((polishing near solution) slurry) SAME (monitor monitors	USPAT;	2003/10/24 14:43
	,	monitoring sense sensor sensors sensing) with turbidity	US-PGPUB;	
			EPO; JPO	
5	26	(monitor monitors monitoring sense sensor sensors sensing)	USPAT;	2003/10/24 13:36
		with turbidity same electromagnetic	US-PGPUB;	
			EPO; JPO	
28	15	("4070797" "4156619" "4563257" "4724042" "5193316"	USPAT	2003/10/24 14:40
		"5320706" "5489233" "5584146" "5616212" "5704987"		
		"5738800" "5759917" "5930645" "6046112"		
		"6120571").PN.		1
29	21		USPAT;	2003/10/24 14:49
	i	monitors monitoring sense sensor sensors sensing) with	US-PGPUB;	
		turbidity	EPO; JPO	
32	1	((polishing near (fluid solution)) slurry) with electromagnetic	USPAT;	2003/10/24 15:17
		with (monitor monitors monitoring sense sensor sensors	US-PGPUB;	
		sensing) same turbidity	EPO; JPO	}
33	1		USPAT;	2003/10/24 14:50
		with (monitor monitors monitoring sense sensor sensors	US-PGPUB;	
	i	sensing) and turbidity	EPO; JPO	
34	2	(fluid solution slurry) with electromagnetic with (monitor	USPAT;	2003/10/24 14:56
		monitors monitoring sense sensor sensors sensing) SAME	US-PGPUB;	
0.5	_	turbidity and (polishing planarization)	EPO; JPO	
35	2	("5291626" "5446531").PN.	USPAT	2003/10/24 14:54
36	2	(fluid solution slurry) with electromagnetic with (monitor	USPAT;	2003/10/24 14:57
		monitors monitoring sense sensor sensors sensing) SAME	US-PGPUB;	
0.7		turbidity and (insulate insulates insulated insulating)	EPO; JPO	
37	0	(fluid solution slurry) with electromagnetic with (monitor	USPAT;	2003/10/24 14:57
		monitors monitoring sense sensor sensors sensing) SAME	US-PGPUB;	
20	١ .	turbidity and (split splitting)	EPO; JPO	
38	3	(fluid solution slurry) with electromagnetic with (monitor	USPAT;	2003/10/24 14:57
	ļ	monitors monitoring sense sensor sensors sensing) and	US-PGPUB:	
43	580	turbidity and (split splitting) 451/\$.ccls. and (semiconductor wafer substrate) and (slurry	EPO; JPO USPAT;	2002/40/24 45:00
75	300	solution) and (supply supplies supplying) and (sensor monitor)	US-PGPUB;	2003/10/24 15:08
		solution) and (supply supplies supplying) and (sensor monitor)	EPO; JPO	
44	7	(451/\$.ccls. and (semiconductor wafer substrate) and (slurry	USPAT;	2003/10/24 15:08
	'	solution) and (supply supplies supplying) and (sensor	US-PGPUB;	2003/10/24 13:00
		monitor)) and turbidity	EPO; JPO	
55	86	(sensor sensors) with (monitor monitors monitoring) with	USPAT;	2003/10/24 15:18
		turbidity	US-PGPUB;	
			EPO; JPO	
-	2496	451/41.ccls.	USPAT;	2003/10/15 16:06
			US-PGPUB;	
			EPO; JPO	
-	8	slurry with (monitor monitoring) with turbidity	USPAT;	2003/10/15 14:45
		,	US-PGPUB;	
			EPO; JPO	
-	281525	electromagnetic slurry with turbidity	USPAT;	2003/10/15 14:36
			US-PGPUB;	
İ	_		EPO; JPO	
-	1	electromagnetic with slurry with turbidity	USPAT;	2003/10/15 14:38
			US-PGPUB;	
	. م	0400000	EPO; JPO	00004545
-	1	6409936.pn.	USPAT;	2003/10/15 14:38
			US-PGPUB;	
		olumn como (monitor monitorino) critic tratta	EPO; JPO	00004045
-	8	slurry same (monitor monitoring) with turbidity	USPAT;	2003/10/15 14:44
			US-PGPUB;	
_	3	(notishing near solution) with (manitar manifestary) with to the tree	EPO; JPO	2002/40/24 42 2 :
-	3	(polishing near solution) with (monitor monitoring) with turbidity	USPAT;	2003/10/24 13:34
		,	US-PGPUB; EPO; JPO	
_	3	(polishing near solution) SAME (monitor monitoring) with	USPAT;	2003/10/22 12:50
i	3	turbidity	US-PGPUB;	2003/10/22 12:50
		- wiwins	EPO; JPO	
	·			

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-	0	09324737.ap.	USPAT;	2003/10/15 14:48
			US-PGPUB;	
			EPO; JPO	
-	5	324737.ap.	USPAT;	2003/10/15 14:48
			US-PGPUB;	
			EPO; JPO	
-	1330	451/5.ccls.	USPAT;	2003/10/15 16:06
			US-PGPUB;	
			EPO; JPO	
-	644	451/6.ccls.	USPAT;	2003/10/15 16:06
			US-PGPUB;	
			EPO; JPO	
-	711	451/8.ccls.	USPAT;	2003/10/15 16:06
			US-PGPUB;	
			EPO; JPO	
-	1305	451/28.ccls.	USPAT;	2003/10/15 16:07
			US-PGPUB;	
			EPO; JPO	
-	796	451/36.ccls.	USPAT;	2003/10/15 16:07
			US-PGPUB;	
			EPO; JPO	
-	410	451/60.ccls.	USPAT;	2003/10/15 16:08
			US-PGPUB;	
			EPO; JPO	
-	4	(451/41.ccls. 451/5.ccls. 451/6.ccls. 451/8.ccls. 451/28.ccls.	USPAT;	2003/10/15 16:09
		451/36.ccls. 451/60.ccls.) and turbidity with (monitor	US-PGPUB;	
		monitoring)	EPO; JPO	
-	14	((polishing near solution) slurry) WITH (monitor monitors	USPAT;	2003/10/22 12:56
		monitoring sense sensor sensors sensing) with turbidity	US-PGPUB;	
			EPO; JPO	
-	20	((polishing near solution) slurry) SAME (monitor monitors	USPAT;	2003/10/24 13:34
		monitoring sense sensor sensors sensing) with turbidity	US-PGPUB;	
	_		EPO; JPO	